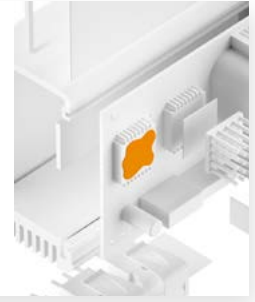
SILICONE GAP FILLER / PUTTY TGL-X-SI

HALA

dispensable

TGL-X-SI is an electrically insulating thermally conductive, highly viscuous dispensable form-in-place gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. The ready-made compound does not require an additional crosslinking process. Due to the specific formulation and filling with ceramic particles the material has a extremly high thermal conductivity. After dispensing the viscoplastic material leads to an optimum thermal contact at no pressure. By its use the total thermal resistance is minimised.



Release 07 / 2023

Technical Data Sheet

PROPERTIESEN

- Dispensable
- Almost zero pressure at assembly due to viscoplasticity
- Thermal conductivity: 6.5 W/mK
- Ready-made, no additional crosslinking required

AVAILABILITY

- Cartridge 50 ml, 300 ml, 5 kg
- Others on request

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- RDRAMs memory modules
- Flip Chips, DSPs, BGAs, PPGAs

For use in Automotive applications / Laptops / Medicine engineering / Industrial PCs / 5G Telecommunication equipment

PROPERTY	UNIT	TGL-X-SI
MATERIAL		Ceramic filled silicone compound
Colour		Orange
Density	g/cm³	3.4
Flow rate	g/s g/min	≥ 30 [1] 3 ~ 4 [2]
Penetration	mm	170
Shelf Life (from Date of Manufacturing, unopened, dry storage conditions @ < 40° C)	Months	6
Flammability (Equivalent)	UL 94	V0
RoHS Conformity	2015 / 863 / EU	Yes
THERMAL		
Thermal Conductivity[3]	W/mK	6.5
Operating Temperature Range	°C	- 40 to + 150
ELECTRICAL		
Dielectric Strength[4]	kV / mm	≥ 4.5
Volume Resistance	Ohm - cm	1.0×10^{14}

Measurement technique according to: [1] ISO 9048, [2] 50 cc / 14#@ 0.42 MPa, [3] ASTM D 5470, [4] ASTM D 149. All data without warranty and subject to change.
Please contact us for further data and information.

All technical data and information are without warranty and believed to be reliable and accurate corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.